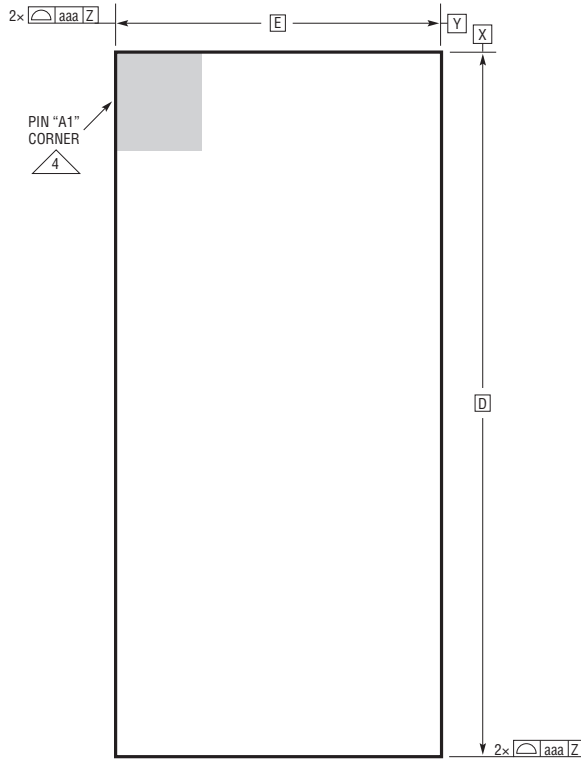
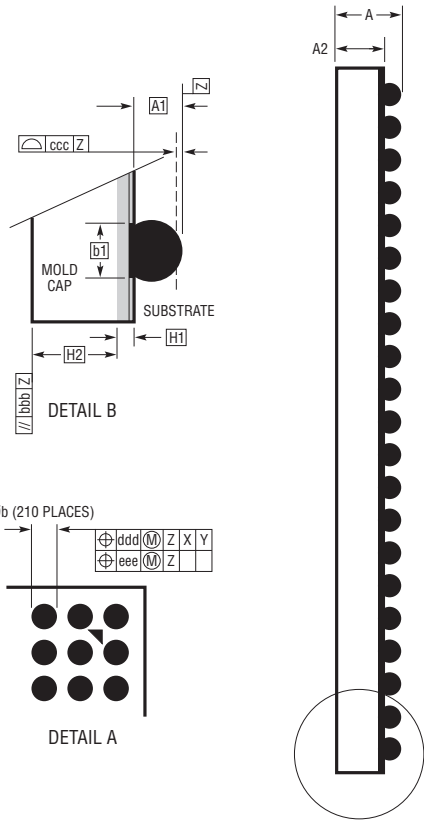


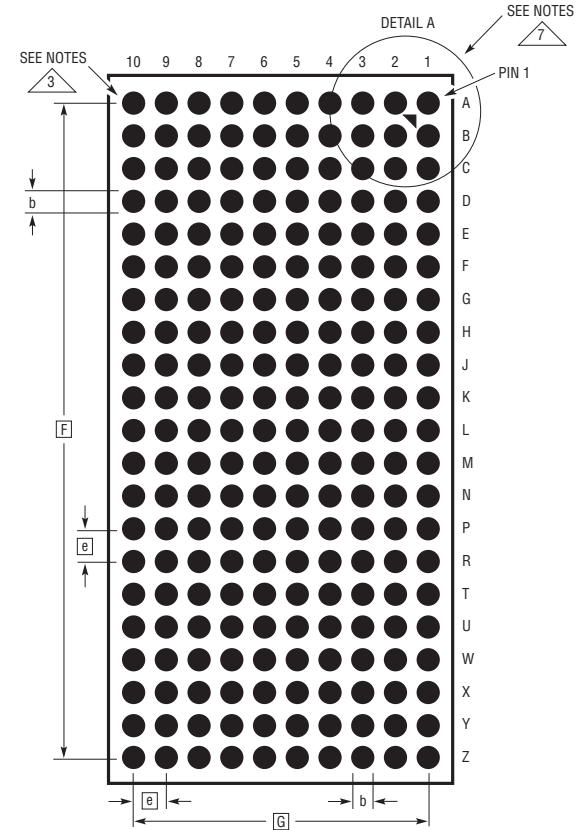
**BGA Package**  
 210-Lead (16.9mm × 8.1mm × 1.52mm)  
 (Reference LTC DWG# 05-08-1828 Rev 0)



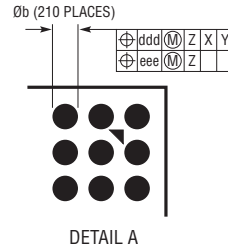
PACKAGE TOP VIEW



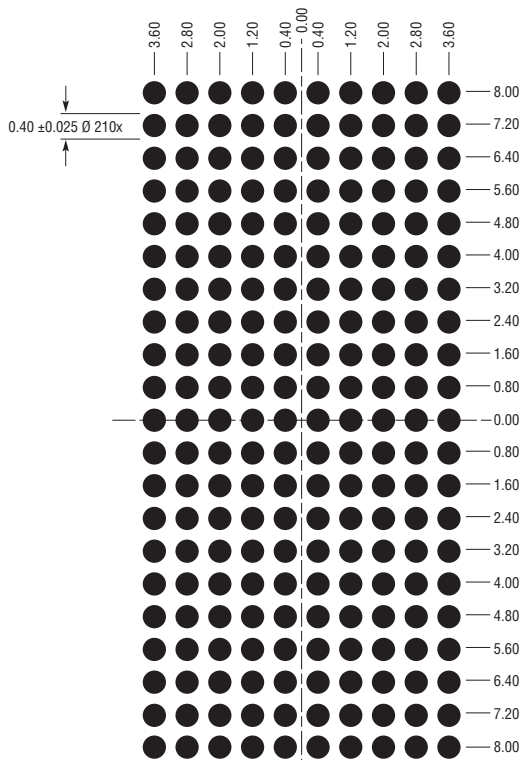
DETAIL B  
 PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



DETAIL A

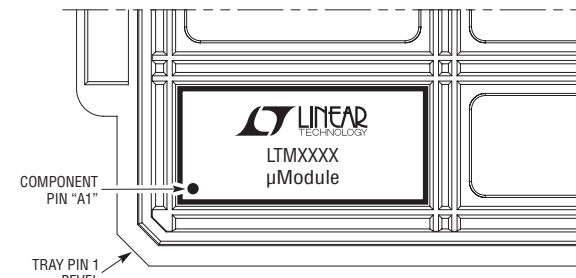


SUGGESTED PCB LAYOUT  
 TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.32	1.52	1.72	
A1	0.30	0.40	0.50	BALL HT
A2	1.02	1.12	1.22	
b	0.35	0.50	0.65	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		16.90		
E		8.10		
e		0.80		
F		16.00		
G		7.20		
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	0.75	0.80	0.85	MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 210				

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
- 3 BALL DESIGNATION PER JEP95
- 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
- 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION